

## N-Channel 60-V (D-S) Fast Switching MOSFET

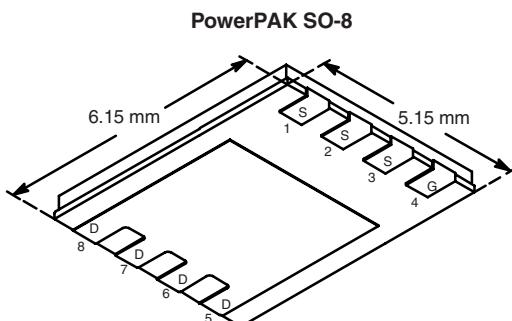
PRODUCT SUMMARY			
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)
60	0.0083 at V <sub>GS</sub> = 10 V	19.3	105

### FEATURES

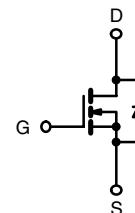
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFET
- New Low Thermal Resistance PowerPAK® Package with Low 1.07 mm Profile
- 100 % R<sub>g</sub> Tested
- High Threshold Voltage At High Temperature



**RoHS**  
COMPLIANT  
**HALOGEN**  
**FREE**  
Available



Bottom View



N-Channel MOSFET

**Ordering Information:** Si7452DP-T1-E3 (Lead (Pb)-free)  
Si7452DP-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS T <sub>A</sub> = 25 °C, unless otherwise noted					
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V <sub>DS</sub>	60		V
Gate-Source Voltage		V <sub>GS</sub>	± 20		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 25 °C	I <sub>D</sub>	19.3	11.5	
	T <sub>A</sub> = 70 °C		15.5	9.2	
Pulsed Drain Current		I <sub>DM</sub>	60		A
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	4.5	1.6	
Avalanche Current		I <sub>AS</sub>	40		
Avalanche Energy		E <sub>AS</sub>	80		
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	P <sub>D</sub>	5.4	1.9	W
	T <sub>A</sub> = 70 °C		3.4	1.2	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C
Soldering Recommendations (Peak Temperature) <sup>b,c</sup>			260		

THERMAL RESISTANCE RATINGS					
Parameter	t ≤ 10 s	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 10 s	R <sub>thJA</sub>	18	23	°C/W
	Steady State		52	65	
Maximum Junction-to-Case (Drain)	Steady State	R <sub>thJC</sub>	1.0	1.3	

Notes:

- Surface Mounted on 1" x 1" FR4 board.
- See Solder Profile ([www.vishay.com/ppg?73257](http://www.vishay.com/ppg?73257)). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

**MOSFET SPECIFICATIONS**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

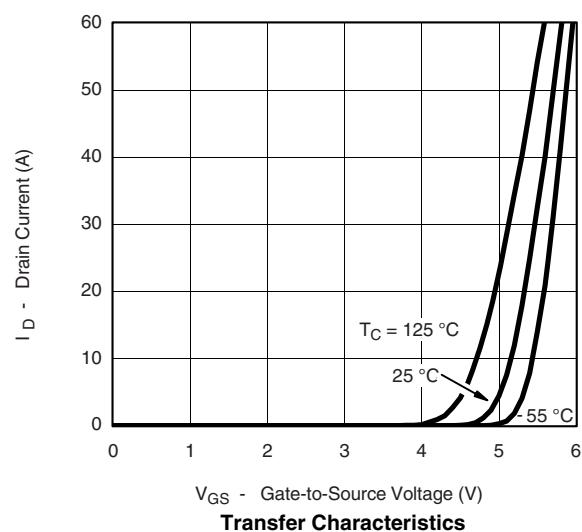
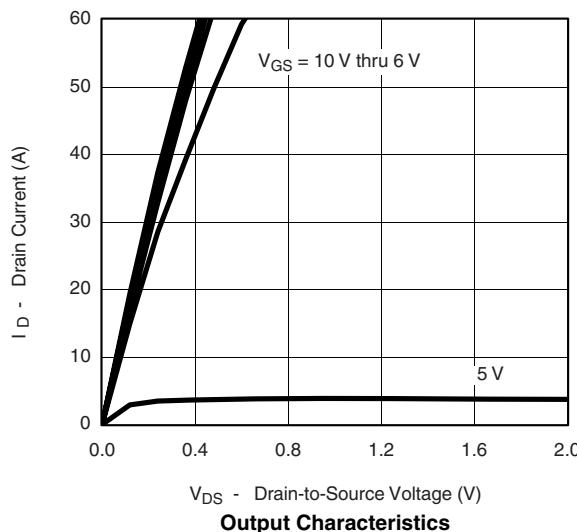
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static</b>						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$	3.4		4.5	V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}$ , $V_{GS} = \pm 20 \text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 60 \text{ V}$ , $V_{GS} = 0 \text{ V}$		1		$\mu\text{A}$
		$V_{DS} = 60 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 55^\circ\text{C}$		5		
On-State Drain Current <sup>a</sup>	$I_{D(\text{on})}$	$V_{DS} \geq 5 \text{ V}$ , $V_{GS} = 10 \text{ V}$	40			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}$ , $I_D = 19.3 \text{ A}$		0.007	0.0083	$\Omega$
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 15 \text{ V}$ , $I_D = 19.3 \text{ A}$		51		S
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = 4.5 \text{ A}$ , $V_{GS} = 0 \text{ V}$		0.8	1.2	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = 30 \text{ V}$ , $V_{GS} = 10 \text{ V}$ , $I_D = 19.3 \text{ A}$		105	160	nC
Gate-Source Charge	$Q_{gs}$			40		
Gate-Drain Charge	$Q_{gd}$			21		
Gate Resistance	$R_g$	$f = 1 \text{ MHz}$	0.5	1.0	1.5	$\Omega$
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = 30 \text{ V}$ , $R_L = 30 \Omega$ $I_D \cong 1 \text{ A}$ , $V_{GEN} = 10 \text{ V}$ , $R_g = 6 \Omega$		45	70	ns
Rise Time	$t_r$			15	25	
Turn-Off Delay Time	$t_{d(\text{off})}$			90	135	
Fall Time	$t_f$			40	60	
Source-Drain Reverse Recovery Time	$t_{rr}$	$I_F = 4.5 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$		46	70	

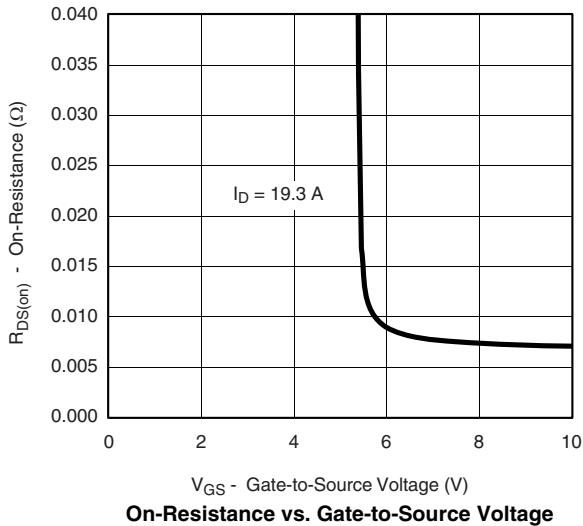
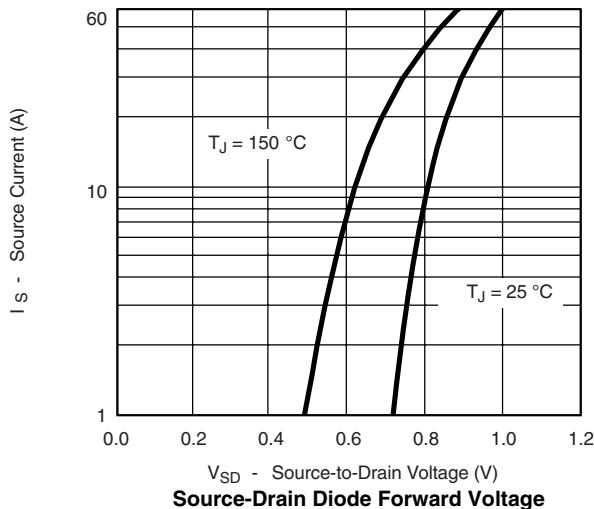
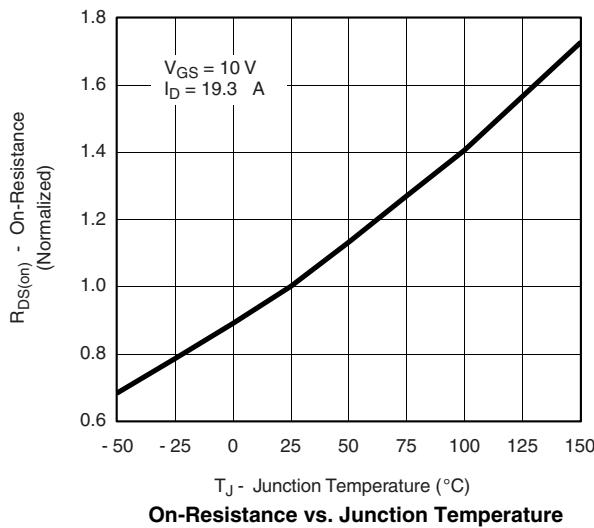
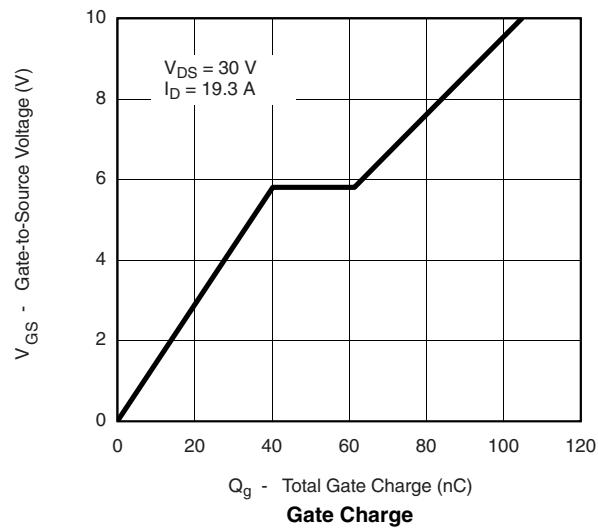
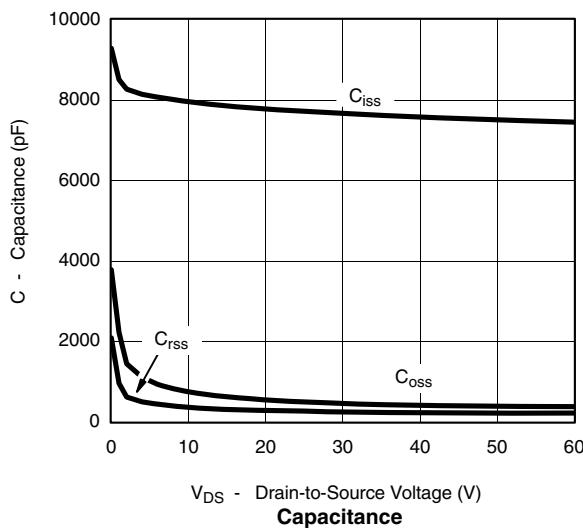
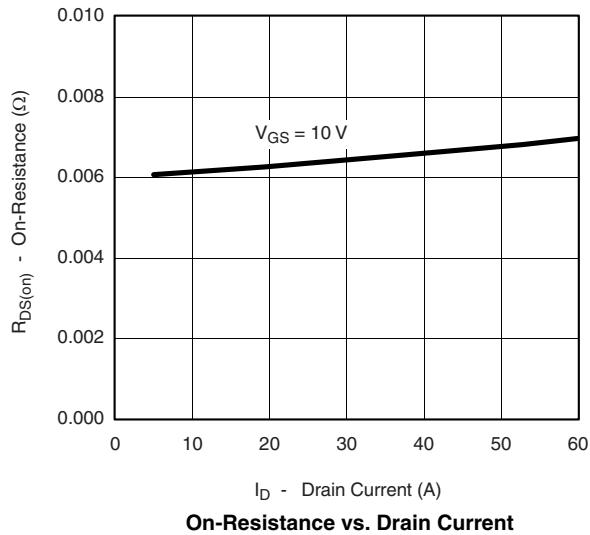
## Notes:

a. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2 \%$ .

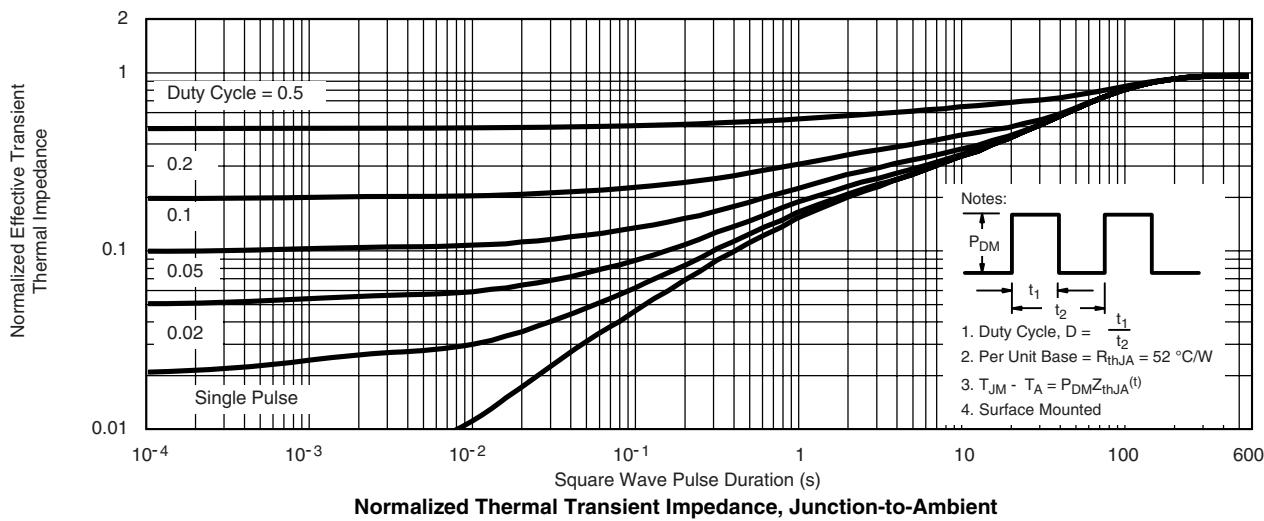
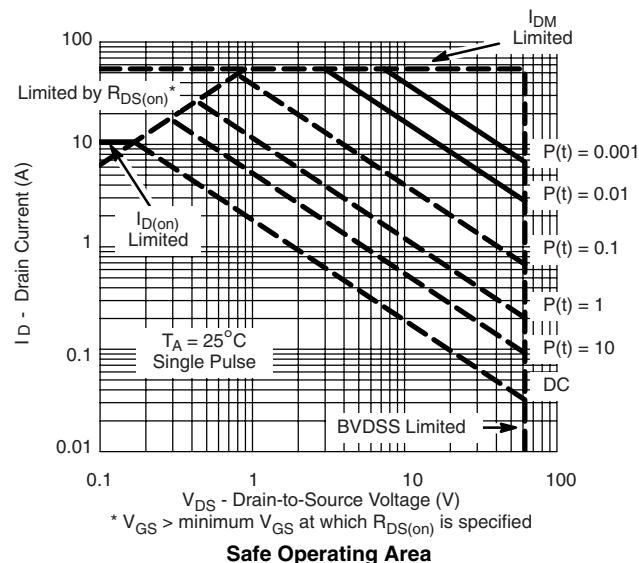
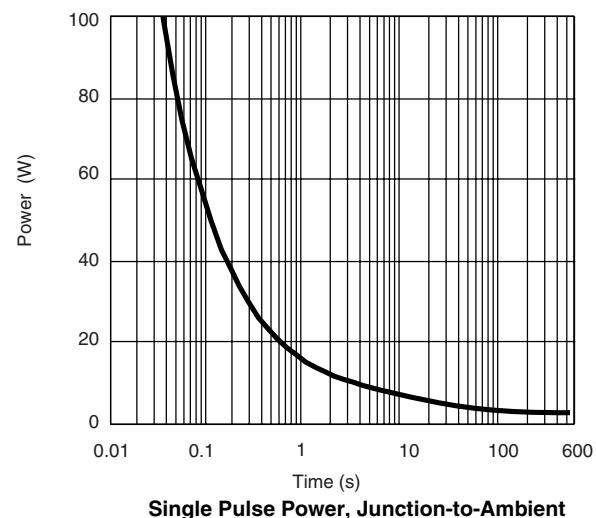
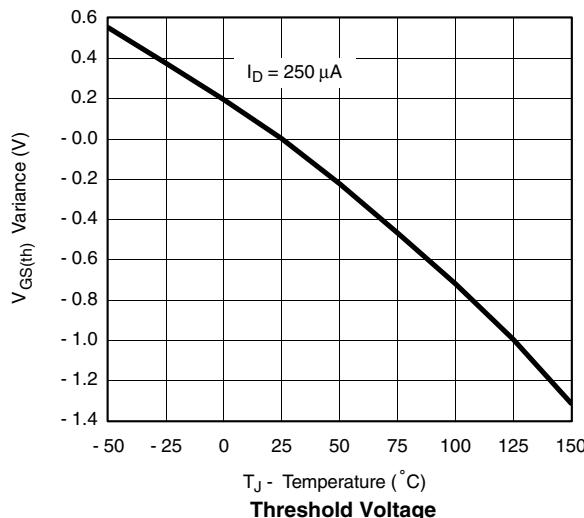
b. Guaranteed by design, not subject to production testing.

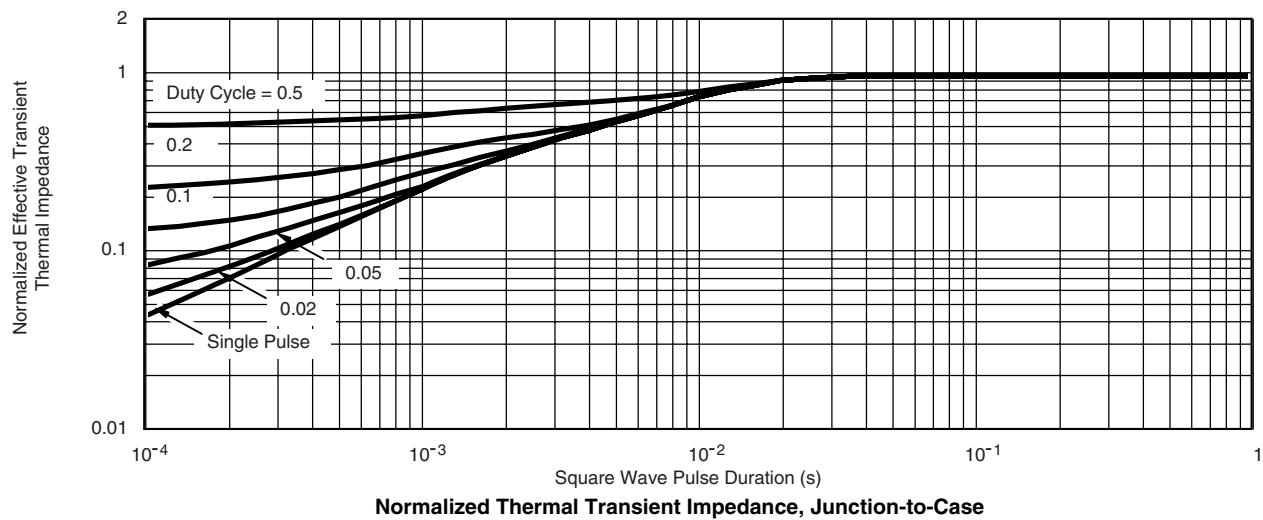
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS**  $25^\circ\text{C}$ , unless otherwise noted


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